

Title (en)  
CONDUCTIVE THERMOSET MOLDING COMPOSITION AND METHOD FOR PRODUCING SAME

Title (de)  
LEITFÄHIGE, WÄRMEHÄRTENDE FORMMASSE SOWIE VERFAHREN ZU IHRER HERSTELLUNG

Title (fr)  
COMPOSITE THERMODURCISSABLE MOULABLE ET SON PROCEDE D'OBTENTION

Publication  
**EP 1023374 A1 20000802 (EN)**

Application  
**EP 98953530 A 19981014**

Priority  
• US 9821748 W 19981014  
• US 6192097 P 19971014

Abstract (en)  
[origin: WO9919389A1] A high filler conductive thermoset composite that may be used in bipolar plates is provided in which the composite may be used to form thin wall, electrically and thermally conductive structures that have sufficient toughness and are resistant to the harsh fuel cell environment.

IPC 1-7  
**C08K 3/04**; **C08K 11/00**; **C08K 5/00**; **H01M 4/00**; **C08G 59/00**

IPC 8 full level  
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CPC (source: EP KR)  
**C08K 3/04** (2013.01 - EP KR); **C08L 63/00** (2013.01 - KR); **H01B 1/24** (2013.01 - EP KR); **H01M 8/0204** (2013.01 - EP KR); **H01M 8/0213** (2013.01 - EP KR); **H01M 8/0226** (2013.01 - EP KR); **C08K 2201/001** (2013.01 - KR); **Y02E 60/50** (2013.01 - EP)

Citation (search report)  
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Cited by  
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**WO 9919389 A1 19990422**; AU 1087599 A 19990503; AU 757196 B2 20030206; BR 9814819 A 20011113; CA 2306144 A1 19990422; CN 1282349 A 20010131; EP 1023374 A1 20000802; JP 2001520245 A 20011030; KR 20010031139 A 20010416; NO 20001925 D0 20000413; NO 20001925 L 20000613

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